



LCD and Camera EMI Filter Array with ESD Protection

CM1431

Features

- Four, six and eight channels of EMI filtering with integrated ESD protection
- Pi-style EMI filters in a capacitor-resistorcapacitor (C-R-C) network
- ±15kV ESD protection on each channel (IEC 61000-4-2 Level 4, contact discharge)
- ±30kV ESD protection on each channel (HBM)
- Greater than 35dB attenuation (typical) at 1 GHz
- TDFN package with 0.40mm lead pitch:
 - 4-ch. = 8-lead TDFN
 - 6-ch. = 12-lead TDFN
 - 8-ch. = 16-lead TDFN
- Tiny TDFN package size:
 - 8-lead: 1.7mm x 1.35mm
 - 12-lead: 2.5mm x 1.35mm
 - 16-lead: 3.3mm x 1.35mm
- Increased robustness against vertical impacts during manufacturing process
- Lead-free finishing

Applications

- LCD and Camera data lines in mobile handsets
- I/O port protection for mobile handsets, notebook computers, PDAs etc.
- EMI filtering for data ports in cell phones, PDAs or notebook computers.
- · Wireless handsets
- Handheld PCs/PDAs
- LCD and camera modules

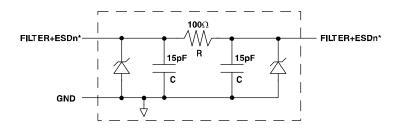
Product Description

The CM1431 is a family of pi-style EMI filter arrays with ESD protection, which integrates four, six and eight filters (C-R-C) in small form factor TDFN 0.40mm pitch packages. The CM1431 has component values of 15pF-100Ω-15pF per channel. The CM1431 has a cut-off frequency of 120MHz and can be used in applications with data rates up to 48Mbps. The parts include ESD diodes on every pin, which provide a very high level of protection for sensitive electronic components that may be subjected to electrostatic discharge (ESD). The ESD protection diodes safely dissipate ESD strikes of ±15kV, well beyond the maximum requirement of the IEC61000-4-2 international standard. Using the MIL-STD-883 (Method 3015) specification for Human Body Model (HBM) ESD, the pins are protected for contact discharges at greater than ±30kV.

These devices are particularly well-suited for portable electronics (e.g. wireless handsets, PDAs, notebook computers) because of their small package and easyto-use pin assignments. In particular, the CM1431 is ideal for EMI filtering and protecting data and control lines for the I/O data ports, LCD display and camera interface in mobile handsets.

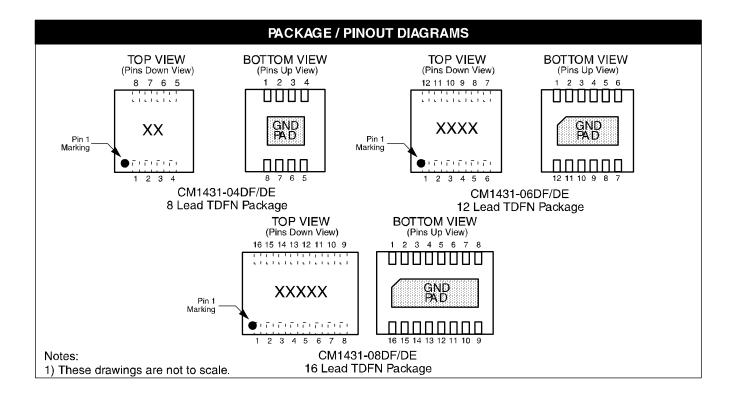
The CM1431 is housed in space-saving, low-profile 8-, 12- and 16-lead TDFN packages with a 0.40mm pitch and is available with lead-free finishing. This smaller size TDFN package provides up to 42% board space saving vs. the 0.50mm pitch TDFN packages.

Electrical Schematic



* See P ackage/Pinout Dia gram for expanded pin information.

1 of 4, 6 or 8 EMI/RFI + ESD Channels



	PIN DESCRIPTIONS										
DE	DEVICE PIN(s)					DE\	DEVICE PIN(s)				
-04	-06	-08	NAME	DESCRIPTION		-04 -06 -08		NAME	DESCRIPTION		
1	1	1	FILTER1	Filter + ESD Channel 1		8	12	16	FILTER1	Filter + ESD Channel 1	
2	2	2	FILTER2	Filter + ESD Channel 2		7	11	15	FILTER2	Filter + ESD Channel 2	
3	3	3	FILTER3	Filter + ESD Channel 3		6	10	14	FILTER3	Filter + ESD Channel 3	
4	4	4	FILTER4	Filter + ESD Channel 4		5	9	13	FILTER4	Filter + ESD Channel 4	
	5	5	FILTER5	Filter + ESD Channel 5			8	12	FILTER5	Filter + ESD Channel 5	
	6	6	FILTER6	Filter + ESD Channel 6			7	11	FILTER6	Filter + ESD Channel 6	
		7	FILTER7	Filter + ESD Channel 7		10		FILTER7	Filter + ESD Channel 7		
		8	FILTER8	Filter + ESD Channel 8				9	FILTER8	Filter + ESD Channel 8	
C	GND PA	D	GND	Device Ground							

Ordering Information

PART NUMBERING INFORMATION									
		Standa	rd Finish	Lead-free Finish					
Pins	Package	Ordering Part Number ¹	Part Marking	Ordering Part Number ¹	Part Marking				
8	TDFN-8	CM1431-04DF	WF	CM1431-04DE	WE				
12	TDFN-12	CM1431-06DF	N31F	CM1431-06DE	N31E				
16	TDFN-16	CM1431-08DF	N318F	CM1431-08DE	N318E				

Note 1: Parts are shipped in Tape & Reel form unless otherwise specified.

Specifications

ABSOLUTE MAXIMUM RATINGS							
PARAMETER	RATING	UNITS					
Storage Temperature Range	-65 to +150	°C					
DC Power per Resistor	100	mW					
DC Package Power Rating	500	mW					

STANDARD OPERATING CONDITIONS						
PARAMETER	RATING	UNITS				
Operating Temperature Range	-40 to +85	°C				

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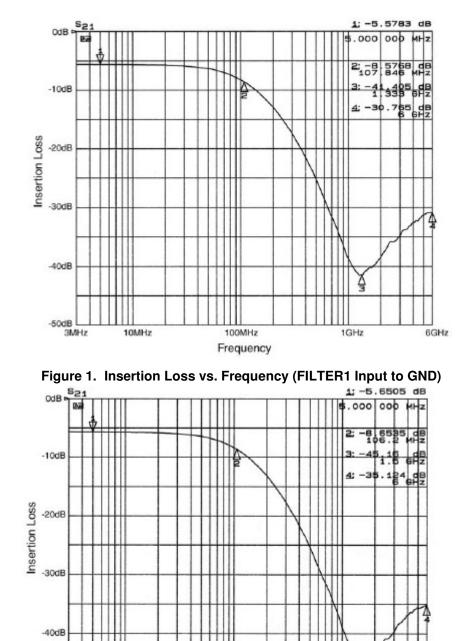
	ELECTRICAL OP	ERATING CHARACTERIS	TICS	(SEE NOTE	1)	
SYMBOL	PARAMETER	CONDITIONS	MIN	ТҮР	МАХ	UNITS
R	Resistance		80	100	120	Ω
$C_{_{TOTAL}}$	Total Channel Capacitance	At 2.5VDC Reverse Bias, 1MHz, 30mVAC	24	30	36	pF
С	Capacitance C	At 2.5VDC Reverse Bias, 1MHz, 30mVAC	12	15	18	pF
V	Standoff Voltage	I _{DIODE} =10μA		6.0		V
I _{leak}	Diode Leakage Current (reverse bias)	V _{DIODE} = 3.3V		0.1	1.0	μA
$V_{\rm SIG}$	Signal Clamp Voltage Positive Clamp Negative Clamp	$I_{LOAD} = 10mA$ $I_{LOAD} = -10mA$	5.6 -1.5	6.8 -0.8	9.0 -0.4	V V
V_{esd}	In-system ESD Withstand Voltage a) Human Body Model, MIL-STD-883, Method 3015 b) Contact Discharge per IEC 61000-4- 2 Level 4	Note 2	±30 ±15			kV kV
$R_{_{DYN}}$	Dynamic Resistance Positive Negative			2.3 0.9		Ω Ω
f_{c}	Cut-off Frequency Z_{SOURCE} =50 Ω , Z_{LOAD} =50 Ω	Channel R = 100Ω, Channel C = 15pF		110		MHz
$A_{_{1GHz}}$	Absolute Attenuation @ 1GHz from 0dB Level	$Z_{\text{SOURCE}} = 50\Omega, Z_{\text{LOAD}} = 50\Omega,$ DC Bias = 0V; Notes 1and 3		35		dB
$A_{_{800MHz-6GHz}}$	Absolute Attenuation @ 800MHz to 6GHz from 0dB Level	$Z_{\text{SOURCE}} = 50\Omega$, $Z_{\text{LOAD}} = 50\Omega$, DC Bias = 0V; Notes 1 and 3		30		dB

Note 1: $T_A=25 \,^{\circ}$ C unless otherwise specified. Note 2: ESD applied to input and output pins with respect to GND, one at a time. Note 3: Attenuation / RF curves characterized by a network analyzer using microprobes.

Performance Information

-50dB 3MHz

10MHz



Typical Filter Performance (T_A=25 °C, DC Bias=0V, 50 Ohm Environment)

Frequency Figure 2. Insertion Loss vs. Frequency (FILTER2 Input to GND)

100MHz

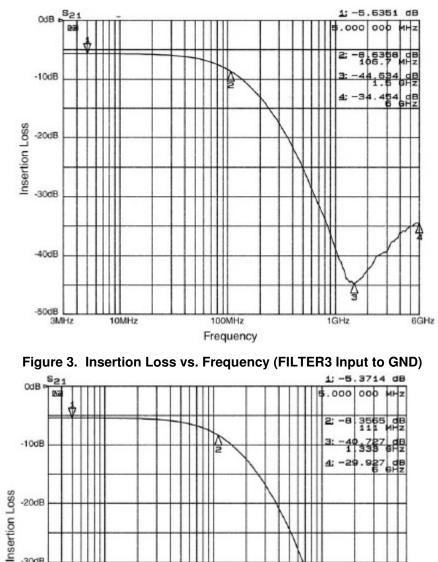
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6GHz

1GHz

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Performance Information (cont'd)



Typical Filter Performance (T₄=25 ℃, DC Bias=0V, 50 Ohm Environment)

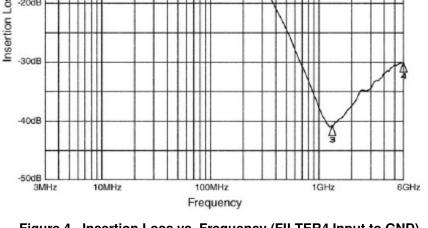


Figure 4. Insertion Loss vs. Frequency (FILTER4 Input to GND)

Performance Information (cont'd)

Typical Diode Capacitance vs. Input Voltage

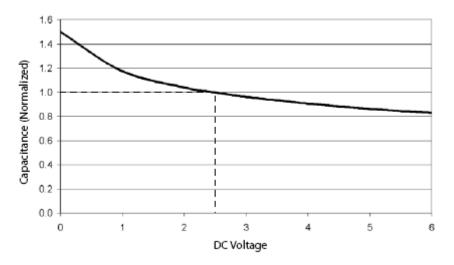


Figure 5. Filter Capacitance vs. Input Voltage (normalized to capacitance at 2.5VDC and 25 °C)

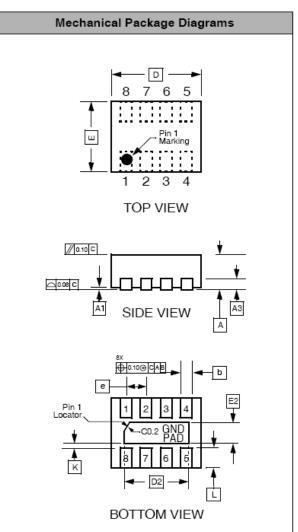
Mechanical Details

CM1431-04DF/DE Mechanical Specifications

Dimensions for the CM1431-04DF/DE supplied in a 8-lead, 0.4mm pitch TDFN package are presented below. For complete information on the TDFN-8, see the California Micro Devices TDFN Package Information document.

	PAC	KAGE	DIME	NSIO	NS				
Package	TDFN								
JEDEC No.	MO-229C [†]								
Leads				8					
Dim.	N	lillimete	ers		Inches				
Dini.	Min	Nom	Max	Min	Nom	Max			
Α	0.70	0.75	0.80	0.028	0.030	0.031			
A1	0.00	0.02	0.05	0.000	0.001	0.002			
A3	(0.20 RE	F	0	0.008 REF				
b	0.15	0.20	0.25	0.006	0.008	0.010			
D	1.65	1.70	1.75	0.065	0.067	0.069			
D2	1.10	1.20	1.30	0.043	0.047	0.051			
E	1.30	1.35	1.40	0.051	0.053	0.055			
E2	0.30	0.40	0.50	0.012	0.016	0.020			
е	(0.40 BS	С	0	.016 BS	C			
к	0.20			0.008					
L	0.15	0.25	0.35	0.006	0.010	0.014			
# per tape and reel			3000	pieces					
	Contro	olling din	nension:	millimet	ters				

[†]This package is compliant with JEDEC standard MO-229C with the exception of the "D", "D2", "E", "E2", "K" and "L" dimensions as called out in the table above.



Dimensions for 8-Lead, 0.4mm pitch TDFN package

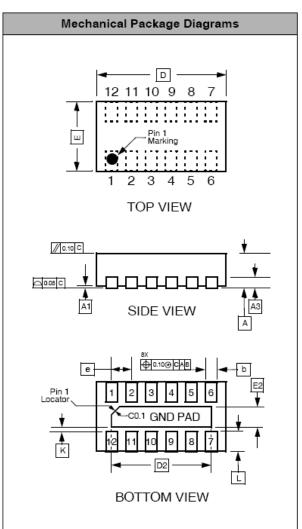
Mechanical Details (cont'd)

CM1431-06DF/DE Mechanical Specifications

Dimensions for the CM1431-06DF/DE suplied in a 12-lead, 0.4mm pitch TDFN package are presented below. For complete information on the TDFN-12, see the California Micro Devices TDFN Package Information document.

	PAC	KAGE	DIME	NSIO	NS				
Package	TDFN								
JEDEC No.	MO-229C [†]								
Leads			1	2					
Dim.	N	lillimete	rs		Inches				
Dini.	Min	Nom	Max	Min	Nom	Max			
А	0.70	0.75	0.80	0.028	0.030	0.031			
A1	0.00	0.02	0.05	0.000	0.001	0.002			
A3	(0.20 RE	F	0	0.008 REF				
b	0.15	0.20	0.25	0.006	0.008	0.010			
D	2.45	2.50	2.55	0.096	0.098	0.100			
D2	1.90	2.00	2.10	0.075	0.079	0.083			
E	1.30	1.35	1.40	0.051	0.053	0.055			
E2	0.25	0.35	0.45	0.010	0.014	0.018			
е	(0.40 BS	С	0	.016 BS	C			
к	0.20			0.008					
L	0.15	0.25	0.35	0.006	0.010	0.014			
# per tape and reel			3000	pieces					
	Contro	olling din	nension:	millimet	ters				

[†]This package is compliant with JEDEC standard MO-229C with the exception of the "D", "D2", "E", "E2", "K" and "L" dimensions as called out in the table above.



Dimensions for 12-Lead, 0.4mm pitch TDFN package

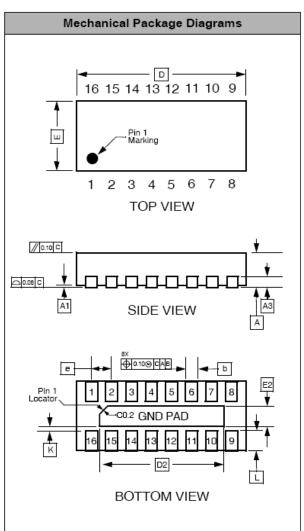
Mechanical Details (cont'd)

CM1431-08DF/DE Mechanical Specifications

Dimensions for the CM1431-08DF/DE supplied in a 16-lead, 0.4mm pitch TDFN package are presented below. For complete information on the TDFN-16, see the California Micro Devices TDFN Package Information document.

	PAC	KAGE	DIME	NSIO	NS				
Package		TDFN							
JEDEC No.	MO-229C [†]								
Leads			1	6					
Dim.	N	lillimete	rs		Inches				
Dini.	Min	Nom	Max	Min	Nom	Мах			
А	0.70	0.75	0.80	0.028	0.030	0.031			
A1	0.00	0.02	0.05	0.000	0.001	0.002			
A3	0.40	0.55	0.70	0.016	0.022	0.028			
b		0.20 RE	F	0	0.008 REF				
D	3.25	3.30	3.35	0.128	0.130	0.132			
D2	2.80	2.90	3.00	0.110	0.114	0.118			
E	1.30	1.35	1.40	0.051	0.053	0.055			
E2	0.35	0.40	0.45	0.014	0.016	0.018			
е	(0.40 BS	0	0	.016 BS	C			
к	0.20			0.008					
L	0.15	0.25	0.35	0.006	0.010	0.014			
# per tape and reel	3000 pieces								
	Contro	olling din	nension:	millimet	ters				

[†]This package is compliant with JEDEC standard MO-229C with the exception of the "D", "D2", "E", "E2", "K" and "L" dimensions as called out in the table above.



Dimensions for 16-Lead, 0.4mm pitch TDFN package

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